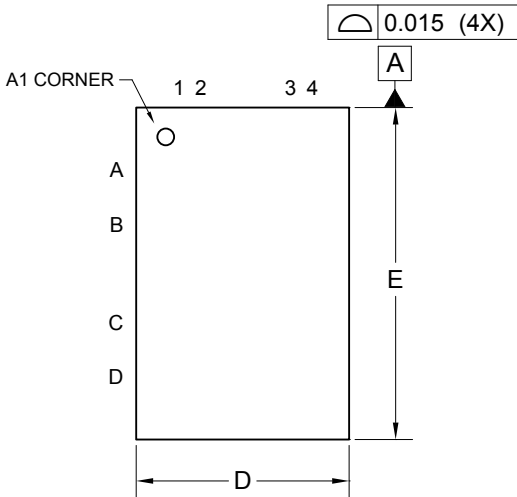
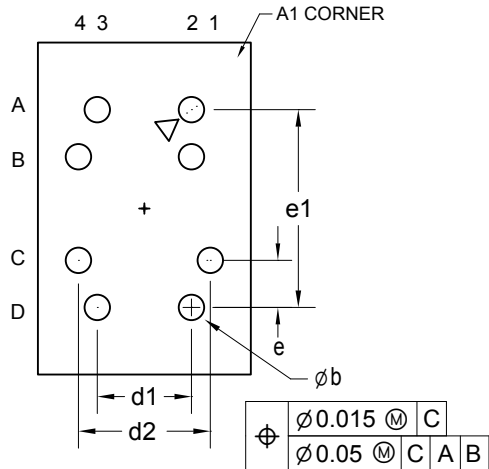


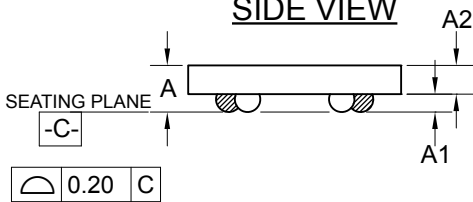
### TOP VIEW



### BOTTOM SIDE



### SIDE VIEW



### PIN ASSIGNMENT MATRIX

	1	2	3	4
A	n/a	V <sub>CC</sub>	NC	n/a
B	n/a	WP	n/a	NC
C	SCL	n/a	n/a	A <sub>2</sub>
D	n/a	SDA	GND	n/a

NC = Not Connected

### COMMON DIMENSIONS (Unit of Measure = mm)

SYMBOL	MIN	TYP	MAX	NOTE
A	0.456	0.495	0.534	
A1	—	0.190	—	
A2	—	0.305	—	
D	Contact Microchip for details.			
d1	1.00 BSC			
d2	1.40 BSC			
E	Contact Microchip for details.			
e	0.50 BSC			
e1	2.10 BSC			
b	—	0.270	—	

Note: 1. Dimensions are NOT to scale.  
2. Solder ball composition is 95.5Sn-4.0Ag-0.5Cu.

4/5/16

### TITLE

8U-18, 8-ball 4x4 Array, Custom Pitch  
Wafer Level Chip Scale Package (WLCSP)

### GPC

GQA

### DRAWING NO.

8U-18

### REV.

01